



# High Performance PPR Copper Plating for HAR Boards

# 高性能脉冲电镀铜及其在高纵横比线路板上的应用

## COPPER GLEAM™ PPR-II Acid Copper

COPPER GLEAM™ PPR-II Acid Copper is specially designed for plating through hole in high aspect ratio boards, working with soluble & insoluble anodes and simple waveform in vertical application.

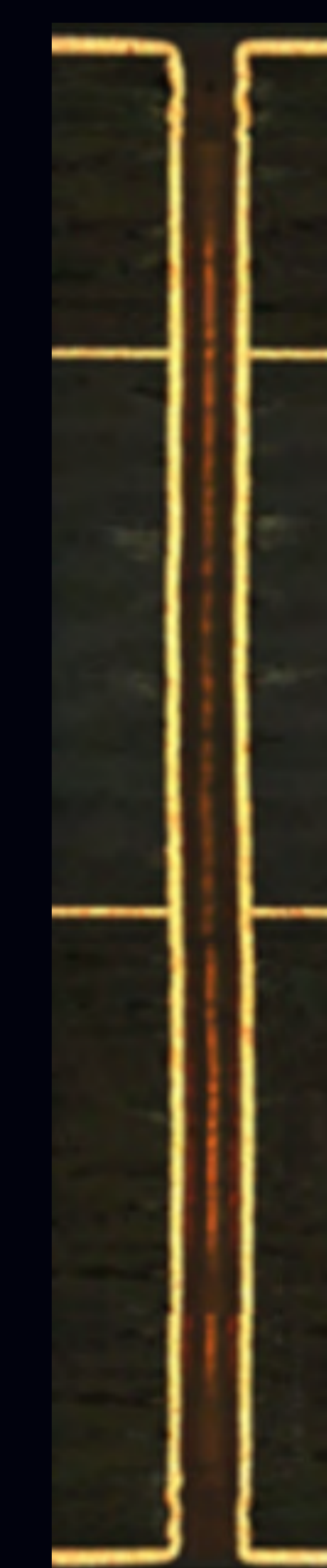
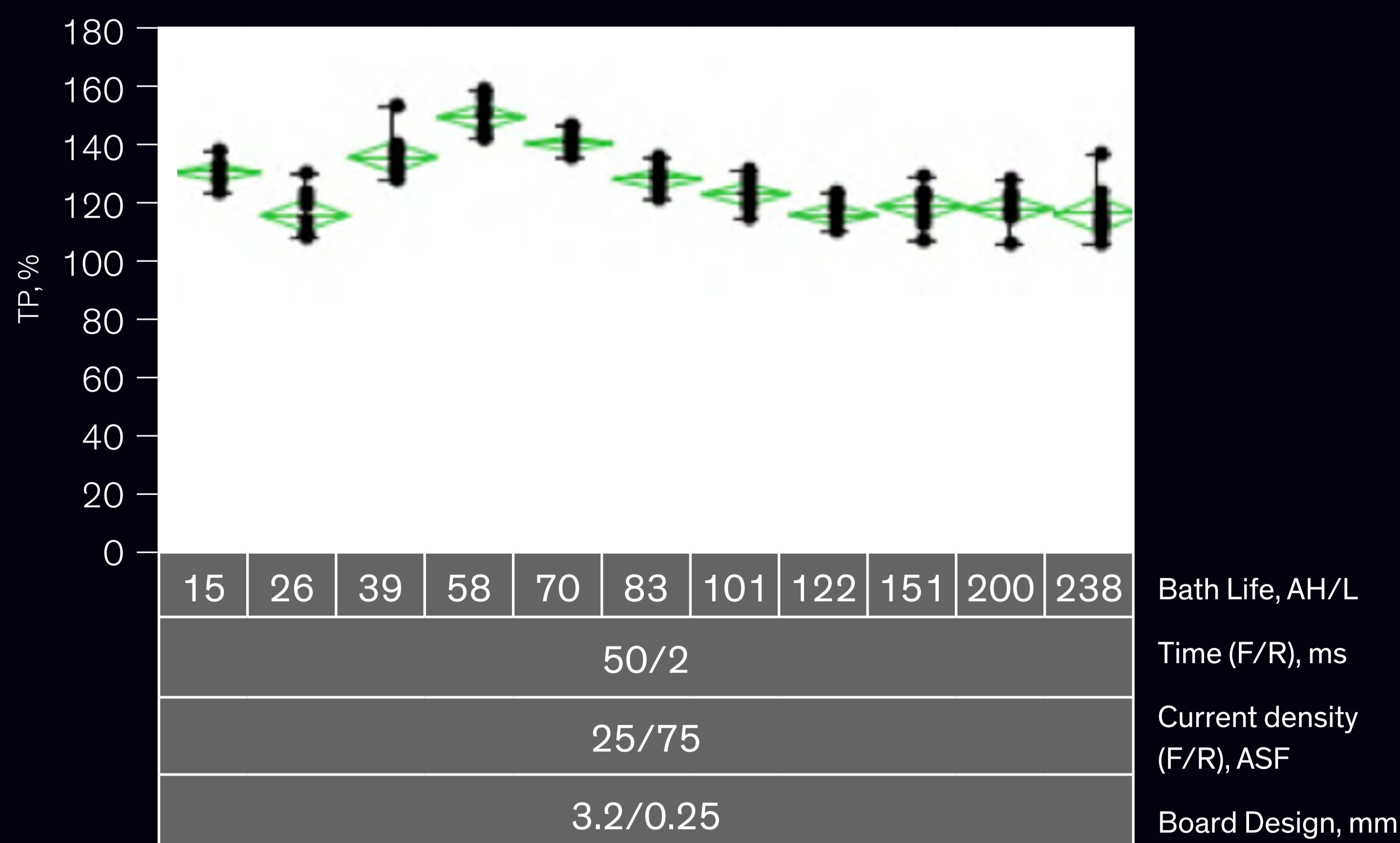
COPPER GLEAM™ PPR-II 专门设计应用于高纵横比之线路板，适用于垂直线可溶性及不溶性阳极，且可透过简易的波形操控。

### Advantages of COPPER GLEAM™ PPR-II COPPER GLEAM™ PPR-II 具备以下优越的特性

- Perform high throwing power for through hole in high aspect ratio of thick boards  
於高纵横比之厚板中，具有高通孔深镀能力之表现
- With outstanding bath stability and easy to restart after idling  
具优越的槽液稳定性及闲置後仅须少量的假镀
- Offer excellent thermal reliability  
提供优越的热稳定性

Outstanding throwing power performance  
优越的通孔深镀能力

Aged bath with consistent TP% performance  
在老化槽液仍有稳定的深镀能力



4.0 mmt/0.2mmØ  
AR = 20  
Hole TP >95%



4.8 mmt/0.3mmØ  
AR = 16  
Hole TP >95%



8.0 mmt/0.5mmØ  
AR = 16  
Hole TP >110%

